

DATA SHEET

ADDENDUM

mifare[®]

MF0 FCP2 U1

Flip Chip Package Specification

Product Specification

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PUBLIC

**Philips
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Flip Chip Package Specification**MF0 FCP2 U1**

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1 SCOPE

This document specifies the products MF0FCP2U10 and MF0FCP2U11:

- The MF0FCP2U10/DH is the integrated circuit MF0ICU10 in the package SOT732CA2.
- The MF0FCP2U11/DH is the integrated circuit MF0ICU11 in the package SOT732CA2.

Therefore this document encompasses all information not covered by the specification of the package and/or the functional specification of the integrated circuit:

- Detailed information on the package is given in the "Specification FCP2 Flip Chip Package".
- Functionality of the integrated circuit is described in the Functional Specification MF0 IC U1.

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2 SPECIFICATIONS

2.1 Integrated Circuit

- Functionality of the integrated circuit is described in the "Functional Specification MF0 IC U1x".

2.2 Absolute Maximum Ratings

ABSOLUTE MAXIMUM RATINGS ^{1, 2}	TEST CONDITIONS	MIN	TYP ¹	MAX	UNIT
Operating Temperature		-25	-	+70	°C
ESD Voltage Immunity	MIL-STD-883-C, Method 3015, Human Body Model C= 100 pF, R = 1.5k Ω	2	-	-	kV _{peak}
Input Current		-	-	30	mA
Storage & Processing Temperature: refer to Package Specification "FCP2 Flip Chip Package"					

NOTES:

- Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the Operating Conditions and Electrical Characteristics section of this specification is not implied.
- This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.

2.3 Electrical Characteristics

T_{op} = - 25 to +70 °C

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP ¹	MAX	UNIT
f _{IN}	input frequency		-	13.56	-	MHz
C _{in}	Input Capacitance between LA - LB ² for the integrated circuit MF0ICU10	22°C, Cp-D, 13.56 MHz, 2 V	14.85		20.13	pF
C _{in}	Input Capacitance between LA - LB ² for the integrated circuit MF0ICU11	22°C, Cp-D, 13.56 MHz, 2 V	42.5		57.5	pF
t _W	EEPROM write time		-	3.8	-	ms
t _{ret}	EEPROM Data Retention	T _{amb} ≤ 55 °C	5	-	-	Years
n _{write}	EEPROM Write Endurance		10 ⁴	-	-	Cycles

NOTES:

- Typical ratings are not guaranteed. These values listed are at room temperature.
- Measured with an HP4258 LCR meter at 13.56 MHz.

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3 ORDERING INFORMATION

Ordering Name	Description	Ordering Code
MF0FCP2U10/DH	Hot laminated transport tape	12NC: 9352 725 94118
MF0FCP2U11/DH	Hot laminated transport tape	12NC: 9352 725 96118

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4 DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics section of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

5 DISCLAIMERS

5.1 Life support applications

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so on their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

Flip Chip Package Specification**MF0 FCP2 U1****6 REVISION HISTORY****Table 1** Addendum Flip Chip Package Specification Revision History

REVISION	DATE	CPCN	PAGE	DESCRIPTION
3.0	Oct 2004	2004 01023		Product version
2.0	Nov 2002			Preliminary version
1.0	June 2002			Initial version

Philips Semiconductors - a worldwide company

Contact Information

For additional information please visit <http://www.semiconductors.philips.com>. Fax: +31 40 27 24825
For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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